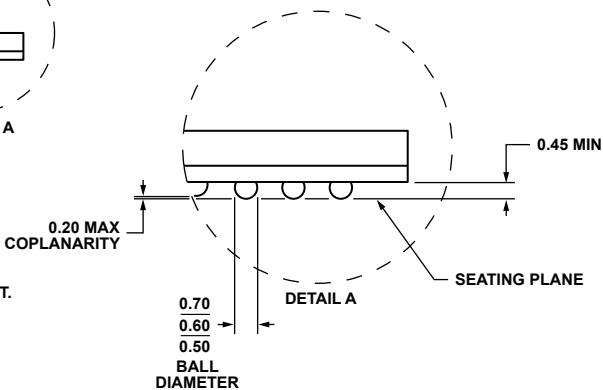
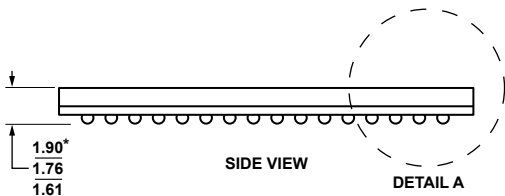
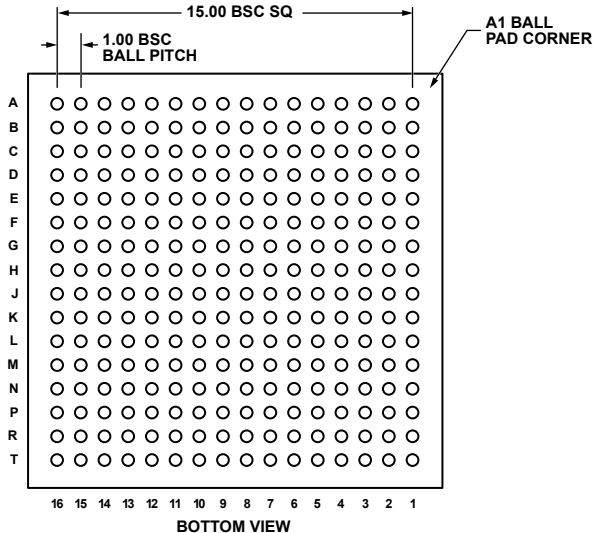
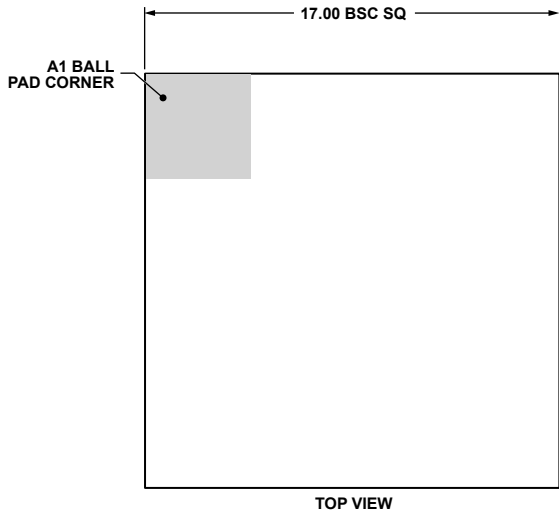


256-Ball Chip Scale Package Ball Grid Array [CSP_BGA]
(BC-256-4)

Dimensions shown in millimeters



*NOTES

1. COMPLIES WITH JEDEC REGISTERED OUTLINE MO-192-AAF-1, WITH EXCEPTION TO PACKAGE HEIGHT.
2. MINIMUM BALL HEIGHT 0.45